



QFB26F

表面安装肖特基桥式整流器

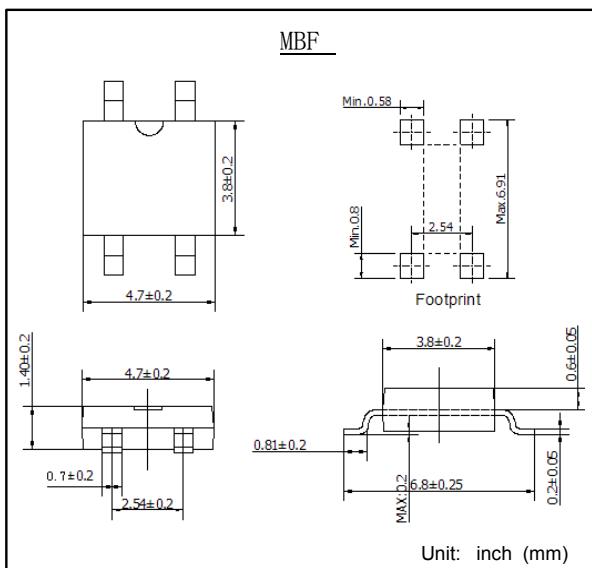
反向电压 60 V

正向电流 2.0 A

Surface Mount Trench Schottky Barrier Bridge Rectifiers

Reverse Voltage 60 V

Forward Current 2.0 A



特征 Features

- 反向漏电流低 Low reverse leakage
- 正向浪涌承受能力强 High forward surge capability
- 高温焊接保证 High temperature soldering guaranteed:
- 260°C/10 秒 260°C/10seconds
- 引线和管体皆符合RoHS标准。 Lead and body according with RoHS standard

机械数据 Mechanical Data

- 封装: MBF 塑封 Case: MBF Molded plastic
- 极性: 标记模压或印于本体 Polarity: Symbols molded or marked on body
- 安装位置: 任意 Mounting Position: Any

最大值和特性 TA = 25°C 除非另有规定。

Maximum Ratings & Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

参数 Parameter	符号 Symbols	QFB26F	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V _{RRM}	60	V
最大均方根电压 Maximum RMS voltage	V _{RMS}	42	V
最大直流阻断电压 Maximum DC blocking voltage	V _{DC}	60	V
最大正向平均整流电流 Maximum average forward rectified current	I _{F(AV)}	2.0	A
正向峰值浪涌电流 1ms单一正弦半波 TA= 25°C Peak forward surge current 1ms single half sine-wave superimposed on rated load	I _{FSM}	50	A
最大正向电压 @IF=2.0A Maximum forward voltage	V _F	0.70	V
最大反向电流 @V _{DC} TA= 25°C Maximum reverse current TA= 100°C	I _R	200 20	μA mA
典型热阻 Typical thermal resistance (Note 1)	R _{θJA} R _{θJL}	105 30	°C/W
典型结电容 VR=4.0V, f=1MHz Type junction capacitance	C _J	280	pF
工作结温 Operating junction temperature rang	T _J	-55 --- +125	°C
存储温度 Storage temperature rang	T _{STG}	-55 --- +150	°C

备注 Note:

1) 安装在PCB板上, 从PN结到环境的热阻。

1) Thermal resistance from junction to ambient , PCB mounted.



特性曲线 Characteristic Curves
